	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
1	BRS	L1	309	257/$.ccls. and (die ic chip substrate board carrier) with stud adj bump	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/30 19:30	
2	BRS	L2	146	438/$.ccls. and (die ic chip substrate board carrier) with stud adj bump	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/30 19:15	
3	BRS	L3	39	29/$.ccls. and (die ic chip substrate board carrier) with stud adj bump	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/30 19:16	
4	BRS	L4	39	361/$.ccls. and (die ic chip substrate board carrier) with stud adj bump	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/30 19:17	

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
5	BRS	L5	29	174/$.ccls. and (die ic chip substrate board carrier) with stud adj bump	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/30 19:17	
6	IS&R	L6	5	(("4908685") or ("6165887") or ("6051450") or ("6165897") or ("20010042781")).PN.	USPAT; US-PGPUB	2004/07/30 19:24	
7	BRS	L11	354	257/$.ccls. and (die ic chip substrate board carrier) with stitch$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/30 19:46	
8	BRS	L12	113	438/$.ccls. and (die ic chip substrate board carrier) with stitch$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/30 19:48	
9	BRS	L13	106	29/$.ccls. and (die ic chip substrate board carrier) with stitch$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/30 19:50	

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
10	BRS	L14	44	361/$.ccls. and (die ic chip substrate board carrier) with stitch$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/30 19:50	